



University Mobility in Asia and the Pacific (UMAP)

International Secretariat

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To: University Coordinators who plan to apply for Super Short-Term Programs (Program C) offered by UMAP member institutions

From: UMAP International Secretariat

Re: Application instructions

We are pleased to announce instructions on how to apply for Super Short-Term Programs (SSTP) to be offered by member institutions of UMAP!

If your students are interested in participating in one of these programs, please advise them to review the information on this website about the programs' contents, length, available credits, and tuition and other fees before applying.

Application forms for each program will be available on the UMAP website beginning 6th April. The application period will run from 6th April until 17th June 2018. Please be noted that there are two cutoff dates, 8th May and 17th June. The application deadline of particular programs are earlier than those cutoff dates and you need to apply in a timely manner depending upon the deadline of each program.

To apply, please complete the following **two steps** before the cutoff date:

- APPLICATION -- **Students** complete the application form for the desired programs in **WORD** format and submit it to the UMAP coordinator at their home university/ institution. The application form can be downloaded from the UMAP website (<http://umap.org/forstudents/>). **Coordinators** collect the submitted applications and send them all together to UMAP International Secretariat by email at umap-is@umap.org
- REGISTRATION -- Please register your name, home university, program(s) you would like to apply for, and other information on UMAP's super short-term programs registration webpage.
https://docs.google.com/forms/d/e/1FAIpQLSeBlpS91et90ubZtFEwtApgnEi_2YzszVicZEXYsiZ5qcaJIQ/viewform

If you have any questions, feel free to contact us.
We look forward to receiving many applications.